

30V N-Channel Power MOSFET

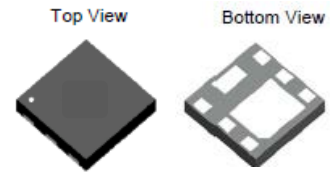
DESCRIPTION :

- Ultra-low $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% Rg Tested
- RoHS compliant
- Pb-Free Lead Plating

V_{DS}	30V
$I_D @ V_{GS}=10V$	29A
$R_{DS(ON)_{Typ.}} @ V_{GS}=10V$	3.7m Ω

TYPICAL APPLICATIONS :

- Power Management
- Current Switching in DC/DC & AC/DC (SR) Sub-system
- Quick/Wireless Charging, Motor Driving



U-DFN2020-6L

3MAXIMUM RATINGS (at $T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	I_D	29 18	A
Pulsed Drain Current ⁽¹⁾		I_{DM}	116	A
Avalanche Current ⁽²⁾		I_{AS}	20	A
Avalanche Energy ⁽²⁾		E_{AS}	20	mJ
Power dissipation	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	P_D	6.3 2.5	W
Junction & Storage temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. This single-pulse measurement was taken under the following condition [$L = 100\mu\text{H}$, $V_{GS} = 10\text{V}$, $V_{DS} = 15\text{V}$] while its value is limited by $T_{J_Max} = 150^\circ\text{C}$.

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta JA}$ $R_{\theta JC}$	85 20	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage $V_{GS} = 0V, I_D = 1000\mu A$	$V_{(BR)DSS}$	30			V
Zero Gate Voltage Drain Current $V_{DS} = 24V, V_{GS} = 0V$	I_{DSS}			1	μA
Gate-Source Leakage Current $V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}			± 100	nA
Gate-Source threshold voltage $V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(th)}$	1.2	1.6	2.5	V
Drain-Source On-State Resistance $V_{GS} = 10V, I_D = 15A$ $V_{GS} = 4.5V, I_D = 10A$	$R_{DS(on)}$		3.7 5.3	4.8 7.0	m Ω
Forward Transconductance $V_{DS} = 5V, I_D = 15A$	G_{FS}		198		S
Input capacitance $f=1MHz, V_{DS}=15V, V_{GS}=0V$	C_{iss}		866		pF
Output capacitance $f=1MHz, V_{DS}=15V, V_{GS}=0V$	C_{oss}		739		pF
Reverse transfer capacitance $f=1MHz, V_{DS}=15V, V_{GS}=0V$	C_{rss}		54		pF
Gate Resistance $V_{DS}=0V, V_{GS}=0V, f=1MHz$	R_g		1.8		Ω
Total Gate Charge $V_{DS}=15V, I_D=15A, V_{GS}=10V$ $V_{DS}=15V, I_D=15A, V_{GS}=4.5V$	Q_G		13.5 6.7		nC
Gate to Source Charge $V_{DS}=15V, I_D=15A, V_{GS}=0$ to 10V	Q_{GS}		2.1		nC
Gate to Drain Charge $V_{DS}=15V, I_D=15A, V_{GS}=0$ to 10V	Q_{GD}		2.0		nC
Turn-on delay time $V_{DS}=15V, V_{GS}=10V, R_L=1.0\Omega, R_{GEN}=6\Omega$	$t_{d(ON)}$		2.4		ns
Rise time $V_{DS}=15V, V_{GS}=10V, R_L=1.0\Omega, R_{GEN}=6\Omega$	t_r		2.5		ns
Turn-off delay time $V_{DS}=15V, V_{GS}=10V, R_L=1.0\Omega, R_{GEN}=6\Omega$	$t_{d(OFF)}$		12.7		ns
Fall time $V_{DS}=15V, V_{GS}=10V, R_L=1.0\Omega, R_{GEN}=6\Omega$	t_f		6.9		ns

Body Diode

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = 1A$	V_{SD}		0.69	1.0	V
Diode Continuous Current, $T_c = 25^\circ\text{C}$	I_S			6	A
Revers Recovery Time $I_F = 15A, di/dt = 100A/\mu s$	T_{rr}		26		ns
Revers Recovery Charge $I_F = 15A, di/dt = 100A/\mu s$	Q_{rr}		10.6		nC

Typical Performance Characteristics

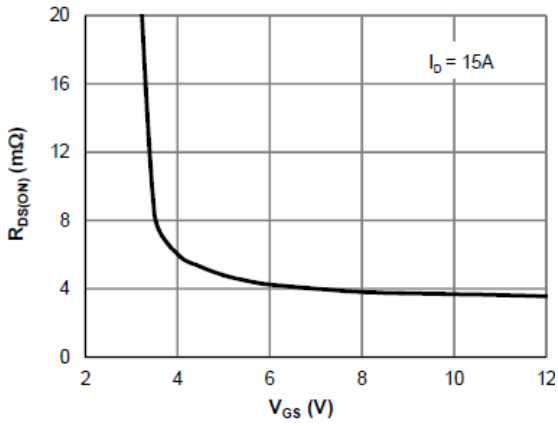


Figure 1. $R_{DS(ON)}$ vs. V_{GS}

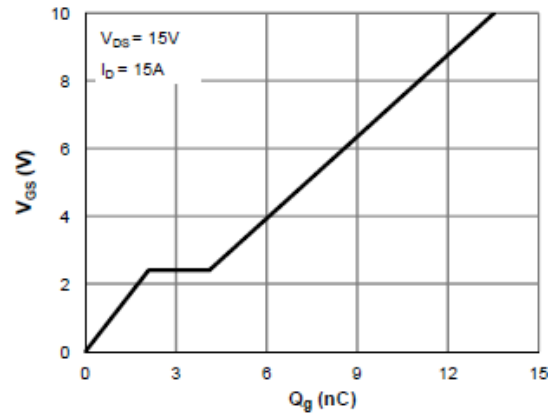


Figure 2. Gate Charge Characteristics

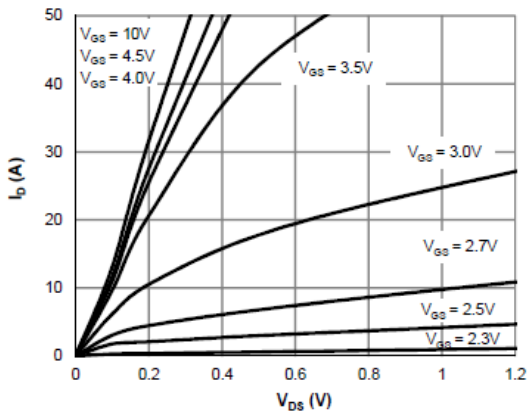


Figure 3. Saturation Characteristics

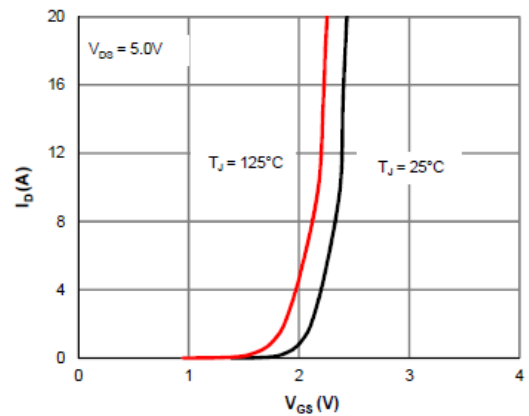


Figure 4. Transfer Characteristics

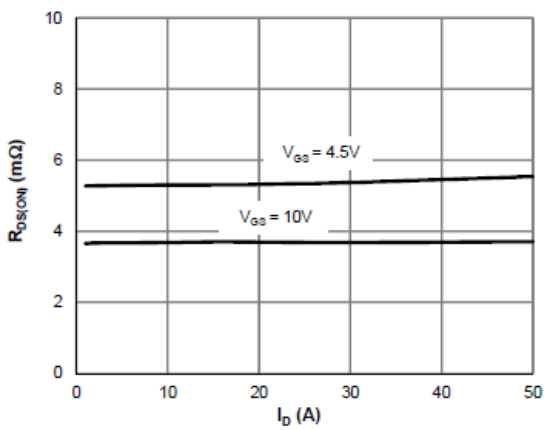


Figure 5. On-resistance vs. Drain Current

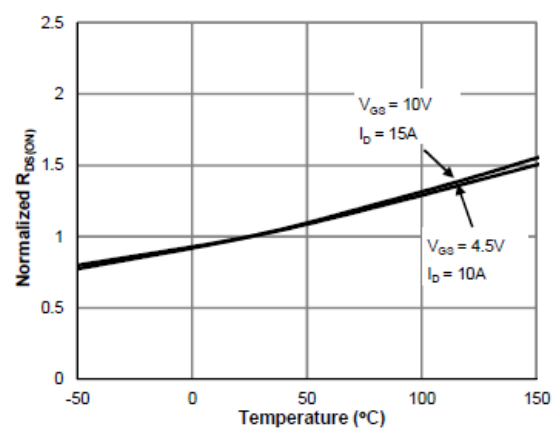


Figure 6. $R_{DS(ON)}$ vs. Junction Temperature

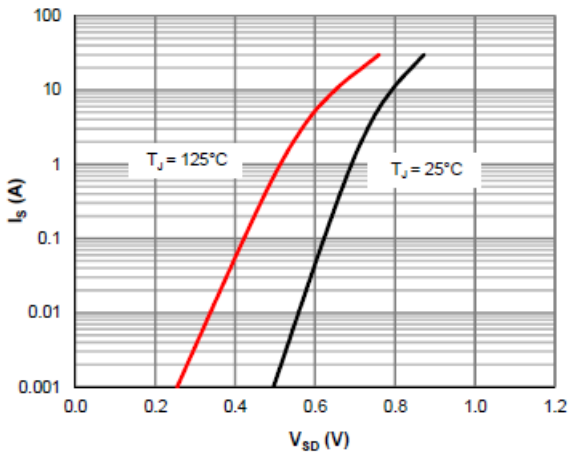


Figure 7. Body-Diode Characteristics

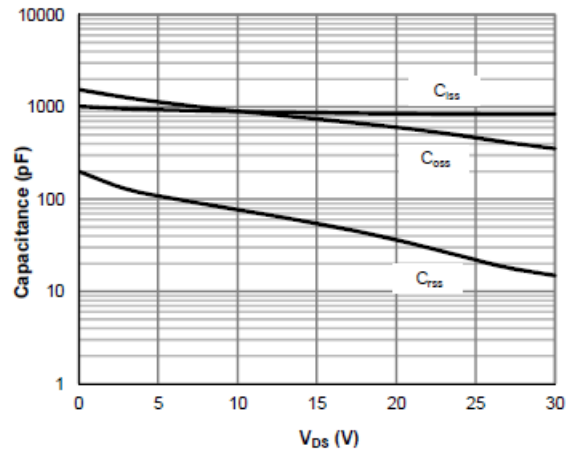


Figure 8. Capacitance Characteristics

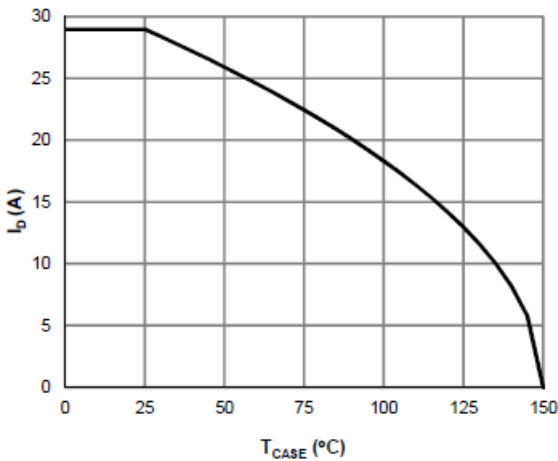


Figure 9. Current De-rating

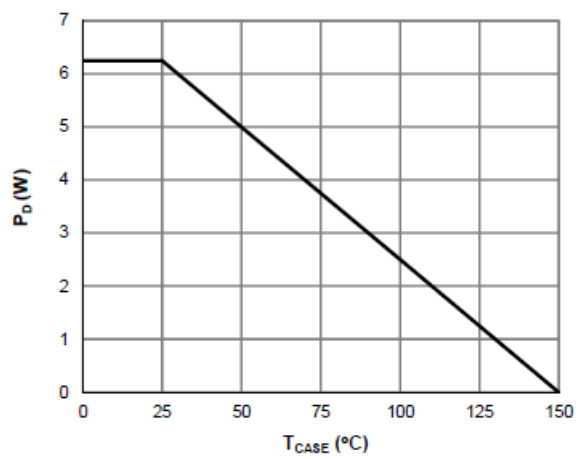


Figure 10. Power De-rating

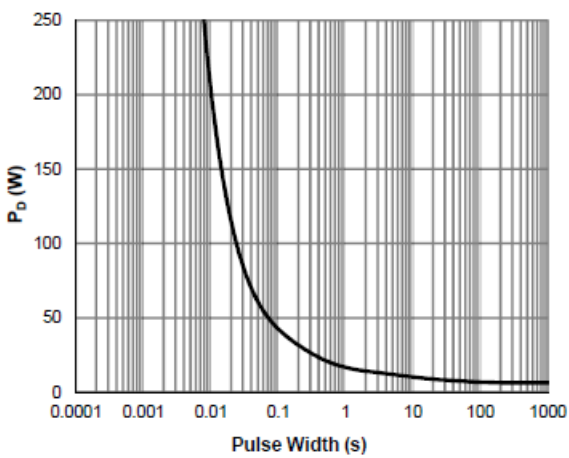


Figure 11. Single Pulse Power Rating, Junction-to-Case

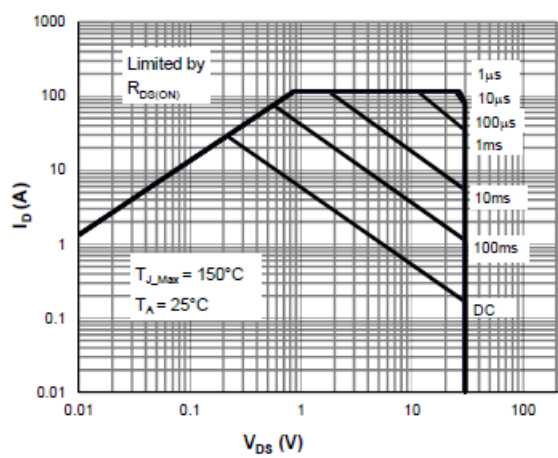


Figure 12. Maximum Safe Operating Area

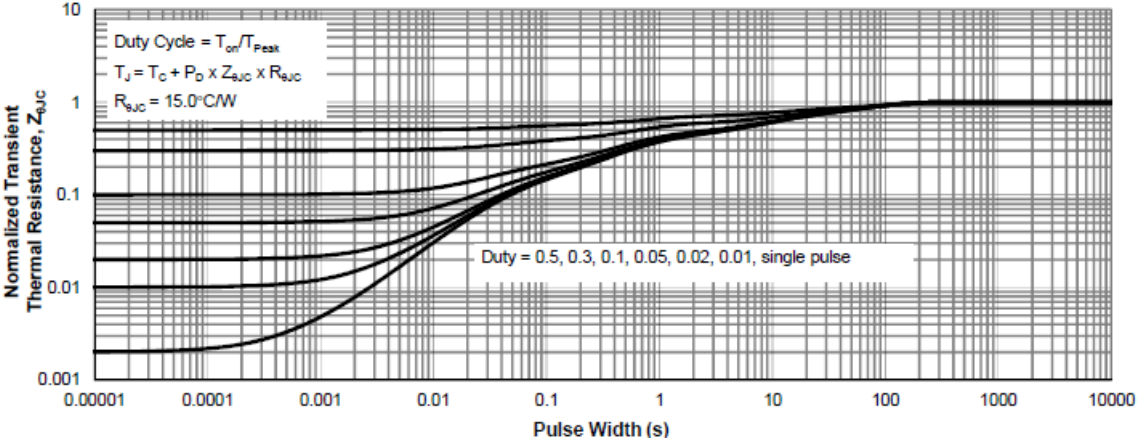
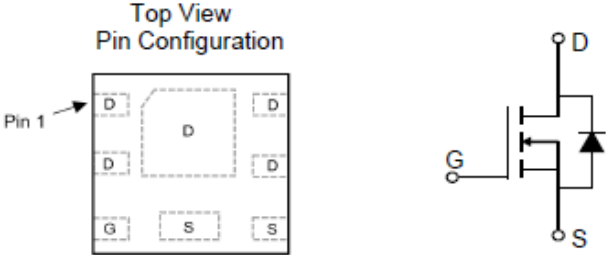
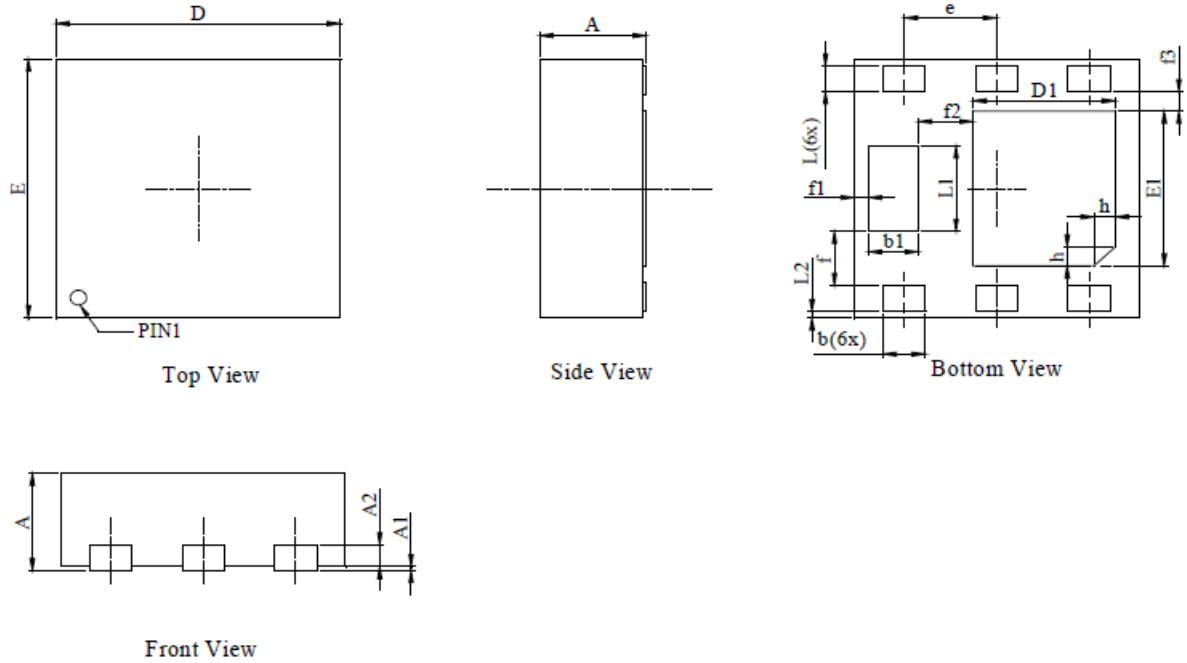


Figure 14. Normalized Maximum Transient Thermal Impedance

• Circuit diagram



• Package outlines : Dimensions in (mm)



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.500	-	0.600
A1	-	-	0.005
A2	-	0.080	0.250
D	1.900	2.000	2.100
E	1.900	2.000	2.100
D1	0.900	1.000	1.100
E1	1.100	1.200	1.300
b	0.250	0.300	0.350
b1	0.300	0.350	0.400
L	0.150	0.200	0.250
L1	0.610	0.660	0.710
L2	0.010	0.050	0.090
e	0.650 BSC		
f	0.420 REF		
f1	0.100 REF		
f2	0.385 REF		
f3	0.150 REF		
h	0.150 REF		

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